



On the HPDP from architecture to a device

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Introduction

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The development of **HPDP** has been initiated by the European Space Agency (ESA) and DLR to address the need for a flexible and re-programmable high performance data processor.

It is being implemented in the 65nm radiation hardened technology of ST Microelectronics.

Key Advantages of HPDP device:

- Ability to meet the increasing requirements of future payloads regarding flexibility, processing power and re-programmability
- Ease of inclusion of late changes (customer or mission requirements)
 Allowance for the adaptation (changes in standards or in higher protocol layers)



HPDP Architecture (1/3)

HPDP device is built around the eXtreme Processing Platform (**XPP**), a runtime reconfigurable data processing engine developed by PACT GmbH.

- 40 ALU Processing Array Elements (16b) running over 300 MHz
- 16 columns RAM blocks for memory
- 2 VLIW processor cores (FNC PAE) running as 125 MHz
- Connected by a reconfigurable data and event network

The XPP array provides:

- High bandwidth data flow processing
- 40Gops through parallelism





HPDP Architecture (2/3)

In addition ...

- 40Mb high speed on chip SRAM, EDAC protected
- Memory interface to external SRAM / SDRAM devices, EDAC protected
- Floating point can be emulated.
- High bandwidth IOs (4 channels with 1.6 Gbps each).
- 3 SpaceWire interfaces at 100 Mbps
- Performant Routing capabilities
- The HPDP is scalable towards multi-chip board architectures
- Any application can be handled by XPP without external µC

Total number of pads: 644 (including redundant stream-IO ports, power and ground)



HPDP Architecture (3/3)

- 40 (5x8) Arithmetic Logic Unit (ALU) processing array elements (PAE)
 - Each ALU consist of three functional sub units, e.g. up to 3 ADD ops/cycle/PAE
 - Each functional sub unit has 16 Bits input / 16 Bits output
 - Very basic functions: ADD, SUB, MUL, ABS, Boolean and shift operations
 - Comparison and Sort
 - Counters and Accumulators
- 16 (2x8) RAM ALU for memory access
- 2 VLIW Functional Controllers
 - Comprised of eight arithmetic logic units
 - 32 KByte instructions and 16 Kbyte of data cache, protected
 - FNC set up the array, the data path and control the DMA units



HPDP Architecture





Comparison with a similar platform

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DEVICE	Maestro	HPDP	
core IP	Tilera TLR26480 Processor	XPP-III 2009 release	
array	49 processor cores	40 ALU PAEs, 16 RAM PAEs	
other processing units	IEEE 754 compliant (single and double precision) floating point unit integrated in each processor	2 FNC-PAEs (RISC like fixed point processors) with L1 instruction and data cache. If floating point calculations are required they can be emulated.	
operating frequency	480 MHz	300 MHz	
I/O throughput	10 Gbps	6.4 Gbps	
Performance	70 GOPS, 14 GFLOPS	> 40 GOPS	
Silicon	90 nm CMOS and radiation hardened by design	65nm CMOS technology of ST Microelectronics. Hardening by process and design	
SW simulator	Yes	Yes, cycle accurate	



Comparison with alternative solutions

	Reconfigurable Arrays	ASIC	DSP	FPGA
Component Development Time & Cost	100%	100%	100%	<mark>200%</mark>
Power Consumption	1	<mark>0.5</mark>	<mark>1</mark>	5
Processing Capability (Performance)	<mark>2.5</mark>	<mark>3</mark>	2	0.2
Flexibility (variable data path)	Yes	No	Almost	Yes
General purpose component	Yes	No	No	No
Average Sales Price per Chip	3	3	1	2

Target Applications (1/2)

 Space debris is a major issue for operational satellites and spacecraft. The detection and tracking of such debris with a good frame rate calls for an efficient on-board image processing scheme.

 Research has been done in order to determine the effectiveness, portability and performance of an image processing algorithm (for space debris) in the HPDP architecture.

Maximum Average Throughput (cycle-accurate): 3.98 Bytes/cycle Performance: determined by memory speed Execution time: 734ms (16bits 2048x2048 pixels input image) Effectiveness: 10% less detected pixels (error negligible)





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Target Applications (2/2)





- Telecom
 - DVB-S Transmitter
 - DVB-S2 Transmitter
 - DVB-S Receiver
 - DVB-RCS Receiver
- In-band TC in Telecom satellites
- Demodulation in intra-satellite optical communications

etc







- ■Temperature -55 °C to +125 °C
- TID Tolerance >100 kRad
- SEL up to 60Mev/mg/cm2 at 125°C
- Lifetime in Orbit 20 Years



Design Flow : On the Hardening

- No Hardening at RTL level
- Full-custom hardened pad ring
- Synthesis with worst case Skyrob cells
- Use of hardened clock buffers during clock tree synthesis
- Hardened PLLs
- Hardened Memory cuts
- Deep n-well mask all over except underneath
 - The pad ring
 - The memory cuts
 - The PLLs



Design Flow : Synthesis and DFT Insertion

- Design Compiler version L-2016.03-SP2
- Modifications for using hardened memory instances
- Synthesis was performed with Skyrob for:
 - Worst case process
 - Worst case voltage (1.10V)
 - Worst case temperature (125C)
 - 20years degradation
- Timing and Area constraints were applied (no multi-scenario)
- DFT insertion: scan chain insertion to be used in scan mode
- Post DFT process: scan enable nets ideal, fix any violated constraint and remove debug interface



Design Flow : Formal Equivalence Check

- It is performed in order to ensure the correctness of the generated design (compare source code with the synthesized netlist).
- Pad Instances and DesignWare Multipliers are handled as black boxes
- The overall process is considered as PASSED (the only failing points are the pins of debug interface, that have been removed during post DFT step).

ISD S.A. Integrated Systems Development

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Design Flow : SDC Files

 All the constraints of the design have been integrated in SDC files, manually written, one for each of the modes:

- func_pll: main functional mode
- func_bypass: functional backup mode, when PLLs are bypassed by primary IO
- func_debug_shift: most of the registers in design are connected in one very long shift-register to allow failure debugging by software
- scan_stuckat_capture: stuck-at capture mode
- scan_stuckat_shift: scan shift mode
- scan_tdf_capture: TDF capture mode
- They are used:
 - In preCTS static timing analysis
 - For the next steps: Place&Route, postCTS static timing analysis (in Primetime type file format)



Design Flow : Place and Route



Characteristics of the final design:

- Dimensions:
 - 9706.6µ x 9577.2µ
 - 93mm2
- 419 IOs (frequency:156,25MHz)

- 4 PLLs with output frequencies:
 - ∎ 1,111 GHz
 - 889 MHz
 - 312,5 MHz
 - 200 MHz
- 82 Memories
 - 57 SPHS
 - 17 DPREG
 - 8 SPREG
- 1 Bandgap
- 8 ESDCLAMP
- ~ 315K sequential cells
- ~ 326K SKYROB cells
- 7.4M instances (~2.1M standard cells and ~5.3M physical instances)



Design Flow : Place and Route

- **Power Mesh**: verified with static IR drop checks.
- Pad Ring: full custom development targeting double row classical wire bond. Special attention has been given to optimize ESD protections and anticipate as much as possible the space qualification of the bonding once packaged.
- Physical sign-off checks applied during the Place and Route process and on the final design:
 - successful Gate2Gate Formal Proof
 - LVS (layout versus schematic) error free
 - DRC antenna and CrossTalk checks error free
 - DRC (design rule check) error free with certain justified rules waived.

Design Flow

Final GDS II





Design Flow : ATPG Automatic Test Pattern Generation

- This step concerns the electronic design automation method used to find an input sequence that, when applied to the design, it enables automatic test to distinguish the correct circuit behavior and the faulty circuit behavior due to defects.
- The produced patterns are used for testing after manufacturing and at wafer and package level or for failure analysis.
- The coverage is almost 96%
- Concerning HPDP design, ATPG process was run in two cases:TDF ATPG
- Stuck-at ATPG

The order is selected so as to reduce the amount of test vectors (TDF pattern also check some stuck-at faults). 20



Design Flow : Static Timing Analysis

- STA is the most important step in the design flow of HPDP, because of its strict timing requirements.
- PreCTS: synthesized netlist and SDC files are used
- PostCTS: post layout/routed netlist, SDC files and SPEF file are used

48 different scenarios are checked, 8 cases for each mode:

- best case, 1.30V, -40C, RCMIN
- best case, 1.30V, -40C, RCMAX
- best case, 1.30V, 125C, RCMIN
- best case, 1.30V, 125C, RCMAX

- worst case, 1.10V, -40C, RCMIN
- worst case, 1.10V, -40C, RCMAX
- worst case, 1.10V, 125C, RCMIN
- worst case, 1.10V, 125C, RCMAX

Checks done:

- successful max transition and max capacitance (with some justified waivers)
- successful setup and hold check, by including CRPR update.
- correct max clock transition
- correct min pulse width check



Design Flow : Post Layout Simulations

For the moment, the following tests have been run:

AHB_DEF_SLAVE1

Description: the specific test concerns the SpW interface and the basic functionality of the design Status: the test is completed successfully

FFT

Description: the specific test concerns the FFT computation Status: FNC starts up correctly and the array is well configured via DMA. Then, it takes time ...



On the package





On the board





On the SW (1/2)

Software Debug Interfaces

- Run Time JTAG Debug Support Interface for register access and array debugging
- Software upload and Software monitoring via SpaceWire
- Multichip Simulation environment

FNC Programming with GNU regular C-Compiler

- For optimization, small kernels in assembler language
- Debugging with low level CPU simulator

Array Programming with native mapping language (NML configuration netlist)

- C to NML converter exists, facilitating the configuration development
- However complex algorithm require manual NML development

The programming approach ...



U. Köthe, VIGRA Library [5]



On the SW (2/2)

- Reed Solomon Encoder according to DVB-S spec, RS(204,188,T=8)
 - Input: Stream of 188 byte frames
 - Output: Stream of 204 byte frames
- Reed Solomon Decoder according to DVB-S spec, RS(204,188,T=8)
 - Input: Stream of 204 byte frames
 - Output: Stream of 188 byte frames
 - Also outputs number of correctable errors
 - Flags uncorrectable packets in TS header

Convolutional Encoder according to DVB-S spec (G1=171oct, G2=133oct)

Selectable FEC 1/2, 2/3, 3/4, 5/6, 7/8

Viterbi Decoder according to DVB-S spec

- Traceback depth configurable (now 512, depends on internal RAM)
- Input: De-punctured soft decision IQ-values (8+8bit)
- Output: Stream of data (2 Byte packed)

QPSK Modulator according to DVB-S spec

- 2/4 times oversampling
- IQ or real output
- Max. 36 tap filter at 4x-oversampling

QPSK Demodulator according to DVB-RCS Spec

- Carrier recovery: Costas-loop with variable parameters
- Timing recovery: Muller&Mueller-loop with variable parameters
- Intersymbol-interference correction by lookuptable
- Input: 2-4 oversampled IQ values
- Output: IQ symbols (8+8bit)

• 32 Point FFT

- Input: 32 complex ordered values (8+8bit)
- Output: 32 complex values (8+8bit)
- Internal twiddle factor table

• 16 tap WOLA filter

- Weighted overlap filter with variable coefficients
- Input: Stream of complex values (8+8)
- Output: Stream of complex values (8+8)



Conclusion

- The HPDP project is a complex design, with many considerations taken into account.
- After a highly iterative process, the GDS II has been generated and the device has been released for manufacturing, considering that all the possible risks have been minimized.
- Applications: HPDP could be used for image processing algorithms (e.g. detecting space debris, telecom), with effectiveness, portability and performance benefits.



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Thank you for your attention!